COST-EFFECTIVE & **DUAL WIPE SOCKETS** 8 Gbps

(2.00 mm) .0787" PITCH • TLE/CLT SERIES

TLE

Mates: ТММН, ТММ, МТММ, MMT, TW, LTMM, ZLTMM, TCMD, TSH

CLT Mates: ТММ, ТММН, МТММ, MMT, TW, TSH

SPECIFICATIONS

TLE Insulator Material:

Black Liquid Crystal Polymer Contact Material: Phosphor Bronze Plating: Au over 50 μ" (1.27 μm) Ni Current Rating (TLE/TMMH): 3.2 A per pin (2 pins powered) Operating Temp Range: -55 °C to +125 °C Insertion Depth: (2.08 mm) .082" to (4.37 mm) .172" with (0.38 mm) .015" wipe, pass-through, or (3.35 mm) .132" min for bottom entry CLT Same as TLE except: Plating: Sn or Au over 50 μ⁺⁺ (1.27 μm) Ni Current Rating (TMMH/CLT): 4.1 A per pin (2 pins powered) Insertion Depth: Top Entry= (1.40 mm) .055" minimum Bottom Entry= (2.57 mm) .101" minimum (add board thickness for correct post OAL) Max Cycles: 100 with 10 μ" (0.25 μm) Au

PROCESSING

TLE Lead-Free Solderable:

Yes SMT Lead Coplanarity:

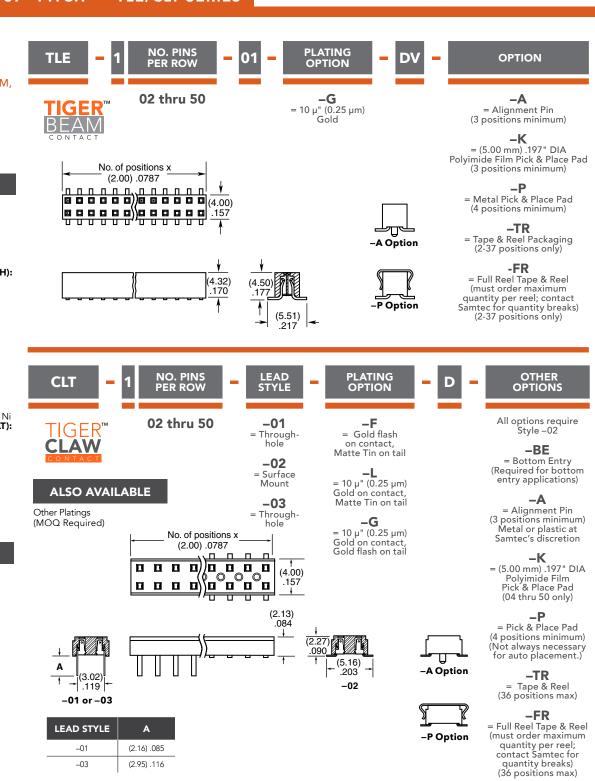
(0.10 mm) .004" max (02-26) (0.15 mm) .006" max (27-50)* *(.004" stencil solution may be available; contact ipg@samtec.com)

ĊLT

CLI Same as TLE except: SMT Lead Coplanarity: (0.10 mm) .004" max (02-25) (0.15 mm) .006" max (26-34)* (0.20 mm) .008" max (35-50)* *(.004" stencil solution may be available; contact ipg@samtec.com)

Note:

Some lengths, styles and options are non-standard, non-returnable



Unless otherwise approved in writing by Samtec, all parts and components are designed and built according to Samtec's specifications which are subject to change without notice.